

# **2016 IEEE 66th Electronic Components and Technology Conference (ECTC 2016)**

**Las Vegas, Nevada, USA  
31 May – 3 June 2016**

**Pages 1-653**



**IEEE Catalog Number: CFP16ECT-POD  
ISBN: 978-1-5090-1205-3**

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IEEE Catalog Number:	CFP16ECT-POD
ISBN (Print-On-Demand):	978-1-5090-1205-3
ISBN (Online):	978-1-5090-1204-6
ISSN:	0569-5503

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